Part Number Customer						
Category	Parameter		Specification	Measurement Method		
OverallWafer	1.0	Diameter	100.00 +/- 0.50 mm	WaferVendor		
	2.0	Primary Flat Orientation	<110> +/- 1 degree	Wafer Vendor		
	3.0	Primary Flat Length	32.50 +/- 2.50 mm	Wafer Vendor		
	4.0	Secondary Flat Orientation	none/semi	Wafer Vendor		
	5.0	Overall Thickness	400.00 +/- 5.00 um	Guaranteed by Process		
	6.0	Total Thickness Variation (TTV)	<5.00um	Guaranteed by Process		
	7.0	Bow	<40.00um	Guaranteed by Process		
	8.0	Warp	<40.00um	Guaranteed by Process		
	9.0	Edge Exclusion	5 mm	Guaranteed by Process		
	10.0	Silicon Supplier	Topsil - handle and device silicon. Cannot be changed without customer approval.	Confirmed Wafer Vendor		
HandleSilicon	11.0	Handle Growth Method	FZ	Wafer Vendor		
	12.0	Handle Orientation	<100> +/- 0.5 degree	Wafer Vendor		
	13.0	Handle Thickness	385.00 +/- 5.00 um	Guaranteed by Process		
	14.0	Handle Doping Type	Ν	Wafer Vendor		
	15.0	Handle Dopant	Phosphorous	Wafer Vendor		
	16.0	Handle Resistivity	1-2 Ohmcm	Wafer Vendor		
	17.0	Backside Finish	Polished with no oxide and lasermark	Wafer Vendor		
DeviceSilicon	18.0	Device Growth Method	FZ	Wafer Vendor		
	19.0	Device Orientation	<100> +/- 0.5 degree	Wafer Vendor		
	19.1	Carbon Concentration	<2E16 atoms/cm3	Wafer Vendor		
	19.2	Oxygen Concentration	<2E16 atoms/cm3	Wafer Vendor		
	20.0	Nominal Thickness	15.00 +/- 0.50 um	FTIR, 100% 9-Pt (note3)		
	21.0	Distance to device silicon edge from wafer edge	<= 2mm	Guaranteed by Process		
	22.0	Device Doping Type	Ν	Guaranteed by Process		
	23.0	Device Dopant	Phosphorous	Guaranteed by Process		
	24.0	Device Resistivity	500-700 Ohmem	Wafer Vendor		
	25.0	Buried Layer Implant	Energy = 40keV, Dose = 1e14, Species = Phosphorous	Implant Vendor		
	26.0	Voids	none	Guaranteed by Process, SAM inspection		
	27.0	Haze	none	Guaranteed by Process, Bright LIght inspection		
	28.0	Scratches	none	Guaranteed by Process, Bright LIght inspection		

Icemos Technology Ltd

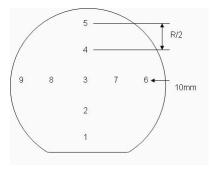
Product Specification

1000.273403

Part Number		Customer		
Category	Parameter	Specification	Measurement Method	
Shipping Details	Wafer per box :	Max 25		
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 100.00mm Antistatic Double Bagging		
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness		
Explanatory Notes	1. Microscope inspect	tion performed using microscope scan as below. 5x objective.		

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information